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forming a third insulating layer over the second insulating layer and pattern of second metallic elements; and

forming a planar capacitor comprising two enmeshed comb shaped electrodes on the third insulating layer.

12. The method of claim 11 wherein the first metallic segments formed on the first insulating layer include a

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segment having a temperature dependent electrical resistance located only over the peripheral portion of the substrate.

13. The method of claim 12 including the further step of providing holes through the first, second and third insulating layers in the central region of the substrate.

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